

ABSTRACT

The present disclosure provides a vacuuming system, a semiconductor process device, and a method for vacuuming the semiconductor process device, and relates to semiconductor technology. The vacuuming system includes: multiple first vacuum pumping components and a second vacuum pumping component. The multiple first vacuum pumping components are connected to the multiple process chamber groups in a one-to-one correspondence. Each first vacuum pumping component includes a first vacuum pump and multiple first vacuum pumping pipelines. Outlet ends of the multiple first vacuum pumping pipelines in each first vacuum pumping component are connected to the first vacuum pump. Inlet ends of the multiple first vacuum pumping pipelines in each first vacuum pumping component are respectively connected one-to-one with the multiple process chambers in each process chamber group. The second vacuum pumping component includes a second vacuum pump and a second vacuum pumping pipeline. An outlet end of the second vacuum pumping pipeline is connected to the second vacuum pump. An inlet end of the second vacuum pumping pipeline is connected to all the process chambers respectively. The semiconductor process device includes the vacuuming system. The method for vacuuming the semiconductor process device is applied to the semiconductor process device. The present disclosure at least solves the problem of a large area being occupied by a conventional device.

FIG. 2